524288-word \times 8-bit High Speed CMOS Static RAM

HITACHI

ADE-203-640A (Z) Rev. 1.0 Dec. 2, 1996

Description

The Hitachi HM628512A is a 4-Mbit static RAM organized 512-kword \times 8-bit. It realizes higher density, higher performance and low power consumption by employing 0.5 µm Hi-CMOS process technology. The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II or 600-mil plastic DIP, is available for high density mounting. The HM628512A is suitable for battery backup system.

Features

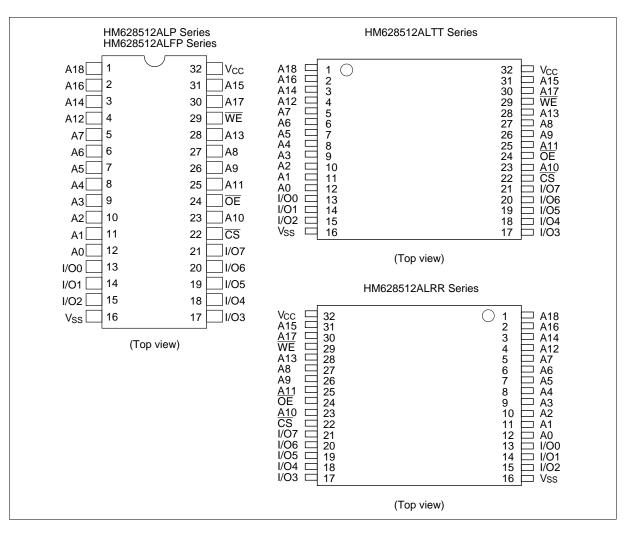
- Single 5 V supply Access time: 55/70 ns (max)
- Power dissipation •
 - Active: 50 mW/MHz (typ)
 - Standby: $10 \mu W$ (typ)
- Completely static memory. No clock or timing strobe required
- Equal access and cycle times
- Common data input and output: Three state output
- Directly TTL compatible: All inputs and outputs
- Battery backup operation



Ordering Information

Туре No.	Access time	Package
HM628512ALP-5 HM628512ALP-7	55 ns 70 ns	600-mil 32-pin plastic DIP (DP-32)
HM628512ALP-5SL HM628512ALP-7SL	55 ns 70 ns	
HM628512ALFP-5 HM628512ALFP-7	55 ns 70 ns	525-mil 32-pin plastic SOP (FP-32D)
HM628512ALFP-5SL HM628512ALFP-7SL	55 ns 70 ns	
HM628512ALTT-5 HM628512ALTT-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II (TTP-32D)
HM628512ALTT-5SL HM628512ALTT-7SL	55 ns 70 ns	
HM628512ALRR-5 HM628512ALRR-7	55 ns 70 ns	400-mil 32-pin plastic TSOP II reverse (TTP-32DR)
HM628512ALRR-5SL HM628512ALRR-7SL	55 ns 70 ns	

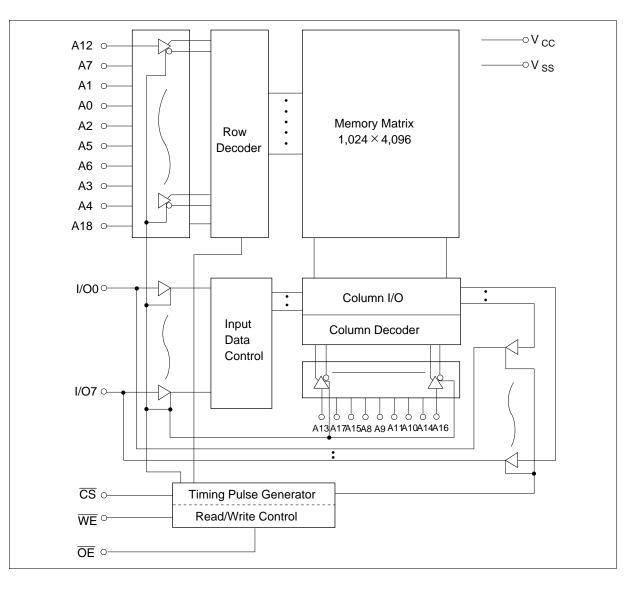
Pin Arrangement



Pin Description

Pin name	Function
A0 to A18	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
ŌĒ	Output enable
WE	Write enable
V _{cc}	Power supply
V _{SS}	Ground

Block Diagram



Function Table

WE	CS	ŌĒ	Mode	V _{cc} current	Dout pin	Ref. cycle
×	Н	×	Not selected	I_{SB},I_{SB1}	High-Z	_
Н	L	Н	Output disable	I _{cc}	High-Z	_
Н	L	L	Read	I _{cc}	Dout	Read cycle
L	L	Н	Write	I _{cc}	Din	Write cycle (1)
L	L	L	Write	I _{cc}	Din	Write cycle (2)

Note: ×: H or L

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage	V _{cc}	–0.5 to +7.0	V
Voltage on any pin relative to V_{ss}	V _T	-0.5^{*1} to V _{cc} + 0.3 ^{*2}	V
Power dissipation	P _T	1.0	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	–55 to +125	°C
Storage temperature under bias	Tbias	-10 to +85	°C

Notes: 1. -3.0 V for pulse half-width ≤ 30 ns

2. Maximum voltage is 7.0 V

Recommended DC Operating Conditions (Ta = 0 to $+70^{\circ}$ C)

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{cc}	4.5	5.0	5.5	V
	V _{ss}	0	0	0	V
Input high voltage	V _{IH}	2.2		V _{cc} + 0.3	V
Input low voltage	V _{IL}	-0.3*1	_	0.8	V

Note: 1. -3.0 V for pulse half-width ≤ 30 ns

DC Characteristics (Ta = 0 to +70°C, $V_{CC} = 5 \text{ V} \pm 10\%$, $V_{SS} = 0 \text{ V}$)

Parameter		Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leakage current		I _{LI}			1	μA	Vin = V_{ss} to V_{cc}
Output leakage current		$ \mathbf{I}_{LO} $	—		1	μA	$\overline{\frac{CS}{WE}} = V_{IH} \text{ or } \overline{OE} = V_{IH} \text{ or} \overline{WE} = V_{IL}, V_{I/O} = V_{SS} \text{ to } V_{CC}$
Operating power supply c	urrent: DC	I _{cc}	—	8	15	mA	$\overline{CS} = V_{IL},$ others = V_{IH}/V_{IL} , $I_{I/O} = 0$ mA
Operating power supply current	HM628512A-5	I _{CC1}	—	45	70	mA	$\label{eq:linear_state} \begin{split} & \underbrace{\text{Min cycle, duty} = 100\%} \\ & \overline{\text{CS}} = \text{V}_{\text{\tiny IL}}, \text{ others} = \text{V}_{\text{\tiny IH}}/\text{V}_{\text{\tiny IL}} \\ & \text{I}_{\text{\tiny I/O}} = 0 \text{ mA} \end{split}$
	HM628512A-7	I _{CC1}	—	40	60	mA	
Operating power supply current		I _{CC2}	_	10	20	mA	$\begin{array}{l} Cycle \ time = 1 \ \mu s, \\ duty = 100\% \\ I_{\text{I/O}} = 0 \ \text{mA}, \ \overline{CS} \leq 0.2 \ \text{V} \\ V_{\text{IH}} \geq V_{\text{CC}} - 0.2 \ \text{V}, \ V_{\text{IL}} \leq 0.2 \\ \text{V} \end{array}$
Standby power supply current: DC		I _{SB}		1	3	mA	$\overline{\text{CS}} = \text{V}_{\text{IH}}$
Standby power supply current (1): DC		I _{SB1}	—	2* ²	100*2	μA	Vin \geq 0 V, $\overline{\text{CS}} \geq$ V $_{\text{CC}}$ – 0.2 V
			—	2* ³	50* ³	μA	_
Output low voltage		V _{OL}		_	0.4	V	I _{oL} = 2.1 mA
Output high voltage		V _{OH}	2.4	_	—	V	I _{OH} = -1.0 mA

Notes: 1. Typical values are at V_{cc} = 5.0 V, Ta = +25°C and specified loading, and not guaranteed.

2. This characteristics is guaranteed only for L version.

3. This characteristics is guaranteed only for L-SL version.

Capacitance (Ta = 25° C, f = 1 MHz)

Parameter	Symbol	Тур	Max	Unit	Test conditions
Input capacitance*1	Cin	_	8	pF	Vin = 0 V
Input/output capacitance*1	C _{I/O}	—	10	pF	$V_{I/O} = 0 V$

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C, $V_{CC} = 5 V \pm 10\%$, unless otherwise noted.)

Test Conditions

- Input pulse levels: 0.8 V to 2.4 V
- Input rise and fall time: 5 ns
- Input and output timing reference levels: 1.5 V
- Output load: 1 TTL Gate + C_L (100 pF) (HM628512A-7)
 - 1 TTL Gate + C_L (50 pF) (HM628512A-5) (Including scope & jig)

Read Cycle

		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read cycle time	t _{RC}	55	_	70	_	ns	
Address access time	t _{AA}	—	55	—	70	ns	
Chip select access time	t _{co}	—	55	—	70	ns	
Output enable to output valid	t _{oe}	—	25	—	35	ns	
Chip selection to output in low-Z	t _{LZ}	10	—	10	—	ns	2
Output enable to output in low-Z	t _{oLZ}	5	_	5		ns	2
Chip deselection to output in high-Z	t _{HZ}	0	20	0	25	ns	1, 2
Output disable to output in high-Z	t _{oHZ}	0	20	0	25	ns	1, 2
Output hold from address change	t _{oH}	10	_	10	_	ns	

Write Cycle

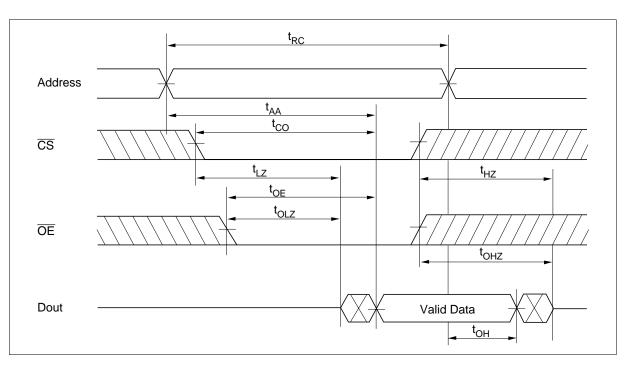
		HM628512A					
		-5		-7		_	
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write cycle time	t _{wc}	55		70	_	ns	
Chip selection to end of write	t _{cw}	50	_	60	_	ns	4
Address setup time	t _{AS}	0		0	_	ns	5
Address valid to end of write	t _{AW}	50		60	_	ns	
Write pulse width	t _{wP}	40	_	50	_	ns	3, 12
Write recovery time	t _{wR}	0	_	0	_	ns	6
WE to output in high-Z	t _{wHZ}	0	20	0	25	ns	1, 2, 7
Data to write time overlap	t _{DW}	25	_	30	_	ns	
Data hold from write time	t _{DH}	0	_	0	_	ns	
Output active from output in high-Z	t _{ow}	5	_	5	_	ns	2
Output disable to output in high-Z	t _{oHz}	0	20	0	25	ns	1, 2, 7

Notes: 1. t_{HZ} , t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

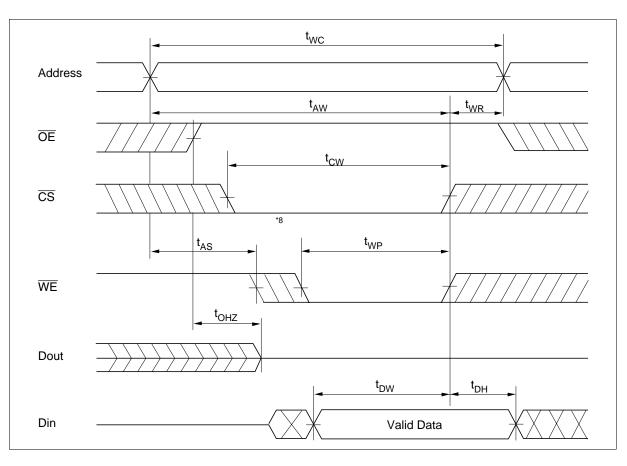
- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap (t_{WP}) of a low CS and a low WE. A write begins at the later transition of CS going low or WE going low. A write ends at the earlier transition of CS going high or WE going high. t_{WP} is measured from the beginning of write to the end of write.
- 4. t_{cw} is measured from \overline{CS} going low to the end of write.
- 5. t_{AS} is measured from the address valid to the beginning of write.
- 6. t_{WR} is measured from the earlier of \overline{WE} or \overline{CS} going high to the end of write cycle.
- 7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 8. If the CS low transition occurs simultaneously with the WE low transition or after the WE transition, the output remain in a high impedance state.
- 9. Dout is the same phase of the write data of this write cycle.
- 10. Dout is the read data of next address.
- 11. If CS is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.
- 12. In the write cycle with \overline{OE} low fixed, t_{WP} must satisfy the following equation to avoid a problem of data bus contention. $t_{WP} \ge t_{DW} \min + t_{WHZ} \max$

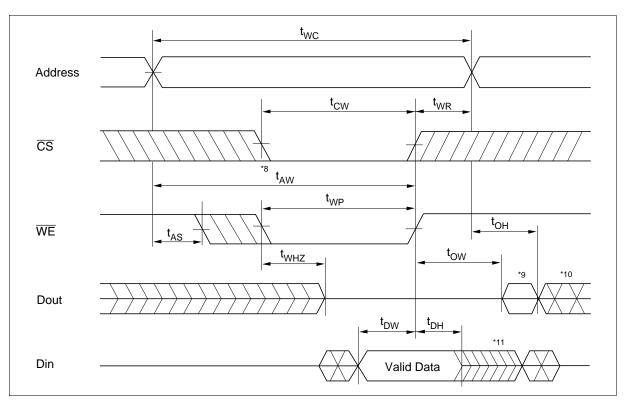
Timing Waveforms

Read Timing Waveform ($\overline{WE} = V_{IH}$)



Write Timing Waveform (1) $(\overline{\text{OE}} \operatorname{Clock})$





Write Timing Waveform (2) (OE Low Fixed)

Low V_{cc} **Data Retention Characteristics** (Ta = 0 to $+70^{\circ}$ C)

Parameter	Symbol	Min	Тур	Max	Unit	Test conditions* ³
V_{cc} for data retention	V_{DR}	2	—	_	V	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V}, \text{ Vin} \ge 0 \text{ V}$
Data retention current	I	_	1 * ⁴	50* ¹	μΑ	$\frac{V_{cc}}{CS} = 3.0 \text{ V}, \text{ Vin} \ge 0 \text{ V}$ $\overline{CS} \ge V_{cc} - 0.2 \text{ V}$
		_	1 * ⁴	15* ²	μΑ	_
Chip deselect to data retention time	t _{CDR}	0	—	—	ns	See retention waveform
Operation recovery time	t _R	5	—	—	ms	

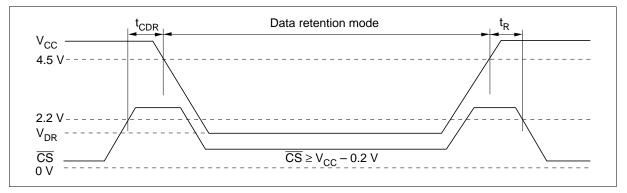
Notes: 1. For L-version and 20 μ A (max.) at Ta = 0 to 40°C.

2. For SL-version and 3 μ A (max.) at Ta = 0 to 40°C.

3. CS controls address buffer, WE buffer, OE buffer, and Din buffer. In data retention mode, Vin levels (address, WE, OE, I/O) can be in the high impedance state.

4. Typical values are at V_{cc} = 3.0 V, Ta = 25°C and specified loading, and not guaranteed.

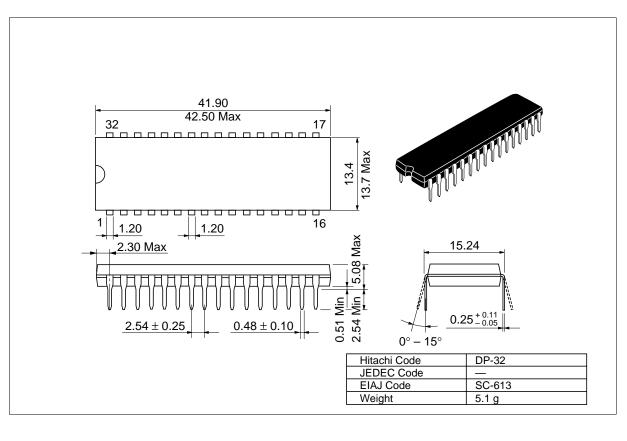
Low V_{CC} Data Retention Timing Waveform $(\overline{CS} \text{ Controlled})$



Package Dimensions

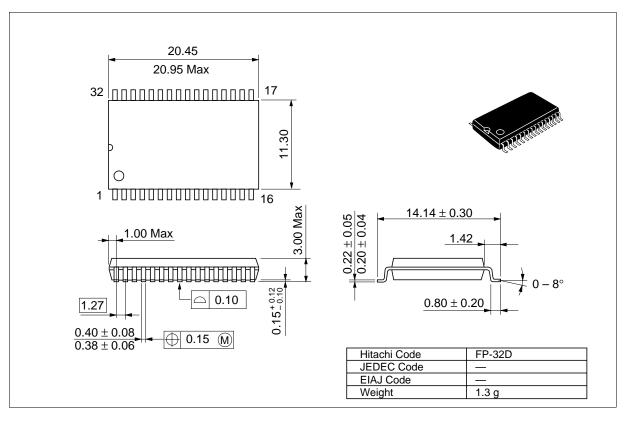
HM628512ALP Series (DP-32)

Unit: mm



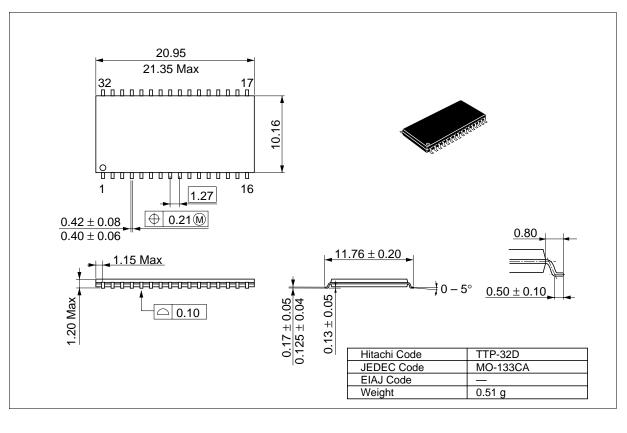
HM628512ALFP Series (FP-32D)

Unit: mm



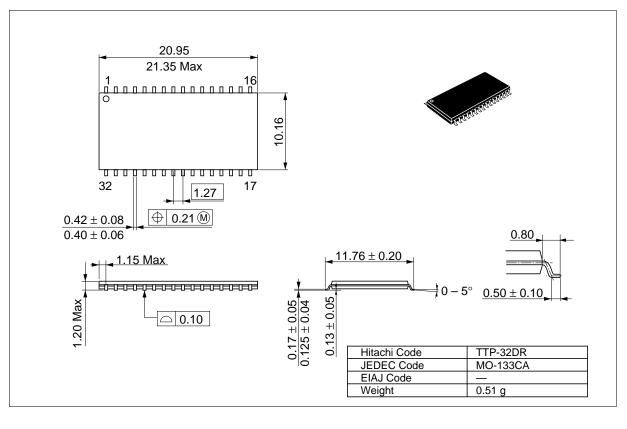
HM628512ALTT Series (TTP-32D)

Unit: mm



HM628512ALRR Series (TTP-32DR)

Unit: mm



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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Sep. 12, 1996	Initial issue	K. Imato	K. Imato
1.0	Dec. 2, 1996	Deletion of preliminary		